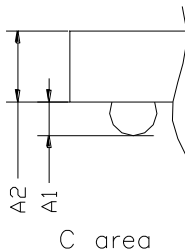
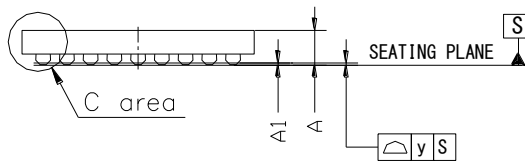
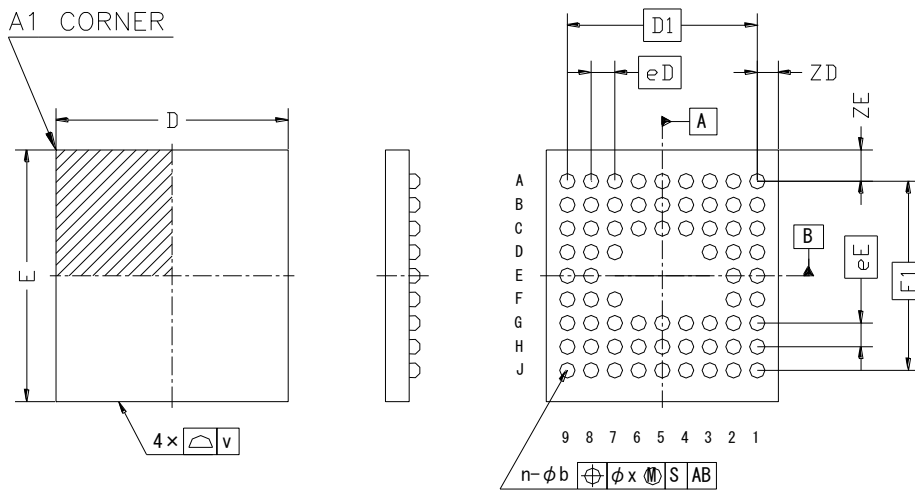


JEITA Package code	RENESAS Code	Previous Code	MASS(TYP.)[g]
S-WFBGA69-3.91x4.26-0.40	SWBG0069LA-A	—	0.02



Dimensions in millimeters

Term	Reference Symbol	Specification		
		Min	Nom	Max
Package length	D	3.86	3.91	3.96
Package width	E	4.21	4.26	4.31
Overhang dimension in length	ZD	0.305	0.355	0.405
Overhang dimension in width	ZE	0.48	0.53	0.58
Profile height	A	—	—	0.70
Stand-off height	A1	0.15	0.19	0.23
Wafer thickness	A2	0.36	0.40	0.44
	(A3)	—	—	—
Terminal diameter	b	0.22	0.27	0.32
Terminal pitch in length	eD	0.4 (BSC)		
Terminal pitch in width	eE	0.4 (BSC)		
Center terminal position in D-direction	SD	— (BSC)		
Center terminal position in E-direction	SE	— (BSC)		
Edge ball center to center in D-direction	D1	3.2 (BSC)		
Edge ball center to center in E-direction	E1	3.2 (BSC)		
Number of terminals	n	69		
Tolerance of package lateral profile	v	0.05		
Positional tolerance of terminals	x	0.05		
Coplanarity	y	0.08		

注記:

- 端子ピッチは端子中央部の位置で規定する。
- データA及びBは、ボールグリッドセンタを称す。

Note:

- Ball pitch dimension is specified with the center of balls.
- Datum A and B are axes defined by the ball grid array, not by the PKG outline.